



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No. 040679/0439

Applicant: Haruhiko MURATA et al.  
Title: IMPROVEMENT IN OR RELATING TO CIRCUIT BOARD HAVING  
SOLDER BUMPS  
Serial No.: 08/825,400  
Filed: March 28, 1997  
Examiner: Cuneo, K.  
Art Unit: 2831

#23/Pat Attc  
R. Tyson  
1/14/02

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AMENDMENT ACCOMPANYING CPA

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination of the above-identified application, please amend the application as follows:

IN THE CLAIMS:

Please cancel claims 1-4 and 12 and please add the following new claims:

13. (New) A circuit board produced by the process of:  
preparing a substrate having a joining surface;  
forming a plurality of solder bumps on the joining surface of the substrate; and  
flattening and levelling tops of the solder bumps.

14. (New) A circuit board according to claim 13, wherein said flattening and levelling comprises pressing a flat surface of a jig against the tops of the solder bumps.

15. (New) A circuit board according to claim 13, wherein said flattening and levelling comprises grinding the tops of the solder bumps.

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